

EV Group Brings Revolutionary Layer Transfer Technology to HVM – December 13, 2023

semiconductor packaging news

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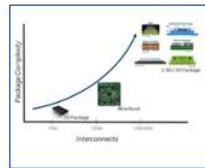
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December 13, 2023

[Closing The Test And Metrology Gap In 3D-IC Packages](#)

The article discusses the critical need for closing the test and metrology gap in 3D integrated circuit (IC) packages. As semiconductor technology advances, 3D IC packages have become more prevalent, but their testing and metrology methods have lagged behind. This ...

Semiconductor Engineering



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The global tech industry is currently embroiled in an intense race to develop nanometer-sized chips, as ...

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[Essential Inspection Requirements in the Era of Convergence](#)

The convergence of semiconductor packaging and board assembly is revolutionizing the industry with innovative inspection machines. This paper explores requirements ...

Technical Paper

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[US updated semi export control to have little effort in stopping China semi development](#)

Digitimes Research reports that China's semiconductor industry is set to experience significant growth in the coming ...

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- [Durability and Cost Benefits Drive Mil-Aero Demand for OCPP](#)
- [Revising 5G RF Calibration Procedures For RF IC Production Testing](#)
- [Optimizing New Power Switch Technology Using Compound Semiconductors](#)
- [Targeted Sample Preparation for Deeply Buried ROI in Advanced Packages](#)
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EV Group

[Advanced Energy Presents Power and Measurement Solutions at SEMICON Japan](#)

Advanced Energy Industries, Inc. will showcase plasma power technologies and complementary products for many stages of the IC ...

Advanced Energy

[STMicroelectronics breaks down barriers to edge AI adoption with free NanoEdge AI deployment](#)

STMicroelectronics is extending its commitment to the rapid adoption of AI in devices that people use everywhere and every day. ...

STMicroelectronics

Decapsulation of Multi-Tier Wire-Bonded Semiconductors

Die Attach Material Comparisons

Packaging high-power GaN devices? This study compares CuW and CMC bases with H2O₂ and AuSn, revealing 34.5°C cooler junctions with CMC/AuSn. Revolutionize GaN efficiency/reliability.
Stratedge Corporation



PacTech's SB²-SMs Quantum

The SB²-SMs Quantum brings contactless & fluxless soldering technology into 3D component soldering. For automated sequential laser soldering, catering to microelectronic devices.
PacTech



Yoon vows full support for S. Korea-Netherlands chip cooperation

China has unveiled its latest supercomputer, Tianhe Xinyi, at the 2023 Supercomputing Innovation Applications Conference in ...

Yonhap News Agency

SUMMARY

China unveils new supercomputer but skips parameters

China has revealed its latest supercomputer, marking a significant stride in the world of high-performance computing. ...

Asia Times

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Samsung, ASML to invest W1 trillion to build research fab in Korea

In a groundbreaking development, South Korea has unveiled plans to launch a nationwide 6G network by ...

The Korea Times

SUMMARY

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Leveraging Reshoring Trends to Generate Economic Growth

The article discusses the potential for economic growth by leveraging reshoring trends. As global supply chain ...

EE Times

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Windows 12 and the coming AI chip war

The tech industry is buzzing with anticipation as Microsoft hints at the release of Windows 12, ...

Computerworld

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Testing ICs Faster, Sooner, And Better

The article discusses advancements in testing integrated circuits (ICs) for improved efficiency and speed. As the ...

Semiconductor Engineering

SUMMARY

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Targeted Sample Preparation for Deeply Buried ROI in Advanced Packages

New fault isolation technique using 3D X-ray microscopy & LaserFIB to pinpoint, isolate & open a 20 μm wirebond without damage to adjacent wires.
ZEISS Microscopy



TSMC bets on AI chips for revival of growth in semiconductor demand

Taiwan Semiconductor Manufacturing Company (TSMC) is placing a strategic bet on AI chips to reinvigorate the ...

Network World

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SEMICON Japan, the largest and most influential gathering of the microelectronics manufacturing supply chain in Japan, opens ...

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Circuit Technology Center



The day was Dec 13. What year was it?

Gore Concedes Presidential Election

Vice President Al Gore reluctantly concedes defeat to Texas Governor George W. Bush in his bid for the presidency, following weeks of legal battles over the recounting of votes in Florida. See the answer below.



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Cartoon of the Day



"When you're feeling overworked, stop and smell the roses that we installed on an app on your phone."


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Calendar

- [Dec 13, 2023: YOLE GROUP WEBAST - CXL: a promising solution to data center memory bottlenecks? webcast](#)
- [Dec 13, 2023: SEMICON Japan 2023](#)
- [Dec 14, 2023: Reflecting on the e-Mobility Industry Trends of 2023 and Predictions for 2024](#)
- [Jan 9, 2024: ISS 2024—Industry Strategy Symposium](#)

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ZEISS Microscopy

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AI Technology



Test Your Knowledge Answer

Which two countries are connected by the Simplon Pass?

Answer: Switzerland and Italy

What Year Was It Answer

Gore Concedes Presidential Election
Answer: December 13, 2000

NEWSLETTER ARCHIVES